

# INTERNATIONAL STANDARD

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**Semiconductor devices - Mechanical and climatic test methods -  
Part 26: Electrostatic discharge (ESD) sensitivity testing - Human body model  
(HBM)**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**Semiconductor devices -  
Mechanical and climatic test methods -  
Part 26: Electrostatic discharge (ESD) sensitivity testing -  
Human body model (HBM)**

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This edition includes the following significant technical changes with respect to the previous edition:

- a) new definitions have been added;
- b) text has been added to clarify the designation of and allowances resulting from “low parasitics”. The new designation includes the maximum number of pins of a device that can pass the test procedure.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47/2963/FDIS	47/2984/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/publications](http://www.iec.ch/publications).

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